



2305A

P-Ch 20V Fast Switching MOSFETs

- ☛ Super Low Gate Charge
- ☛ Green Device Available
- ☛ Excellent CdV/dt effect decline
- ☛ Advanced high cell density Trench technology

Product Summary

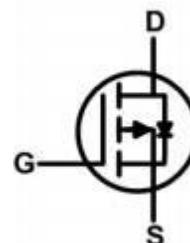
BVDSS	RDS(ON)	ID
-20V	28mR	-5.0A

Description

The 2305A is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The 2305A meet the RoHS and Green Product requirement with full function reliability approved.

SOT 23 Pin Configurations



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-20	V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-5.0	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-3.0	A
I _{DM}	Pulsed Drain Current ²	-16	A
P _D @T _A =25°C	Total Power Dissipation ³	1.31	W
P _D @T _A =70°C	Total Power Dissipation ³	0.84	W
T _{STG}	Storage Temperature Range	-55 to 150	C
T _J	Operating Junction Temperature Range	-55 to 150	C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	125	C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤ 10s)	---	---	C/W



Electrical Characteristics ($T_J=25^\circ C$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-20V, V_{GS}=0V,$	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 12V$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.7	-1.0	V
$R_{DS(on)}$ note2	Static Drain-Source on-Resistance	$V_{GS}=-4.5V, I_D=-4.1A$	-	28	35	$m\Omega$
		$V_{GS}=-2.5V, I_D=-3A$	-	38	53	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=-10V, V_{GS}=0V,$ $f=1.0MHz$	-	830	-	pF
C_{oss}	Output Capacitance		-	132	-	pF
C_{rss}	Reverse Transfer Capacitance		-	85	-	pF
Q_g	Total Gate Charge	$V_{DS}=-10V, I_D=-2A,$ $V_{GS}=-4.5V$	-	8.8	-	nC
Q_{gs}	Gate-Source Charge		-	1.4	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	1.9	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=-10V, I_D=-3.3A,$ $R_G=1\Omega, V_{GEN}=-4.5V$	-	10	-	ns
t_r	Turn-on Rise Time		-	32	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	50	-	ns
t_f	Turn-off Fall Time		-	51	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	-5.0	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-16	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_s=-4.1A$	-	-	-1.2	V

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$



Typical Performance Characteristics

Figure 1: Output Characteristics

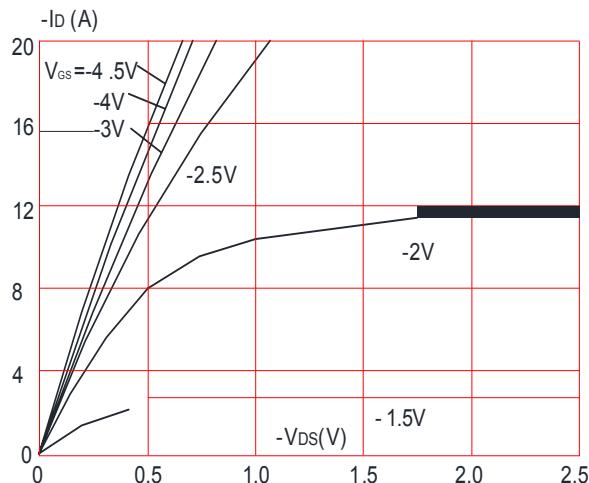


Figure 2: Typical Transfer Characteristics

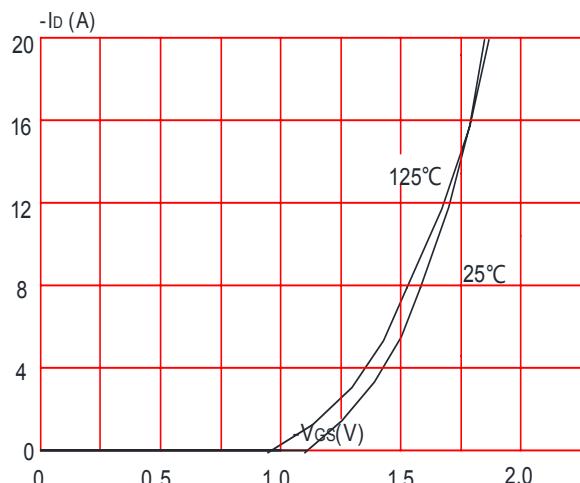


Figure 3: On-resistance vs. Drain Current

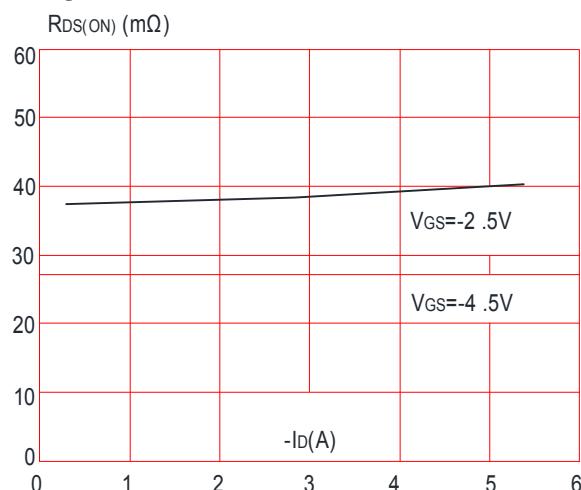


Figure 5: Gate Charge Characteristics

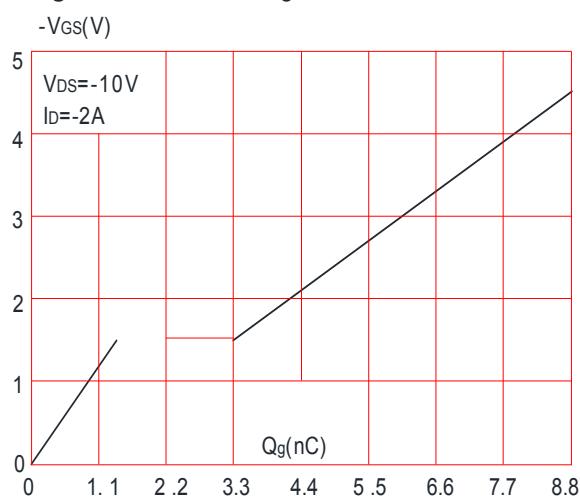


Figure 4: Body Diode Characteristics

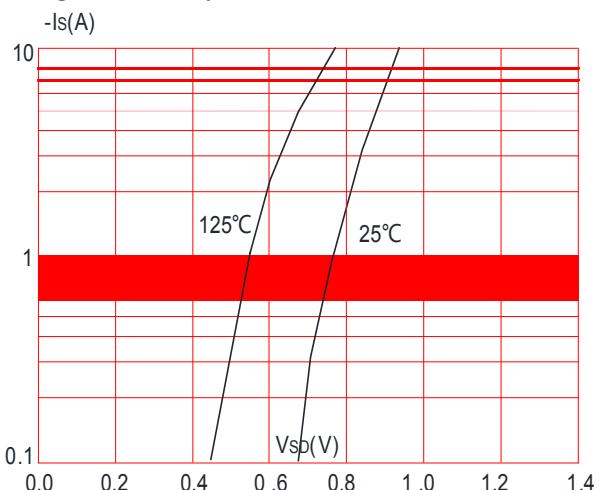


Figure 6: Capacitance Characteristics

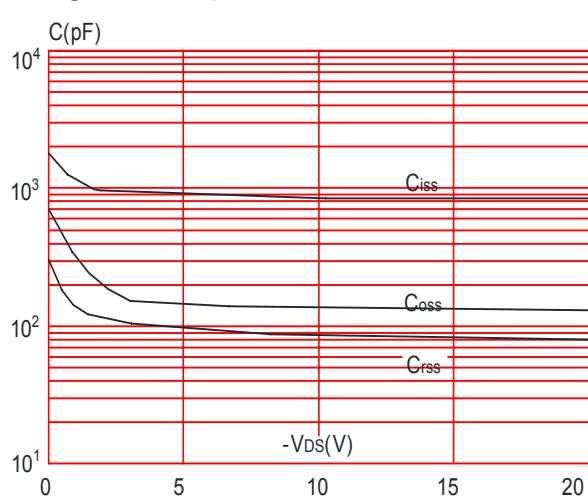




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

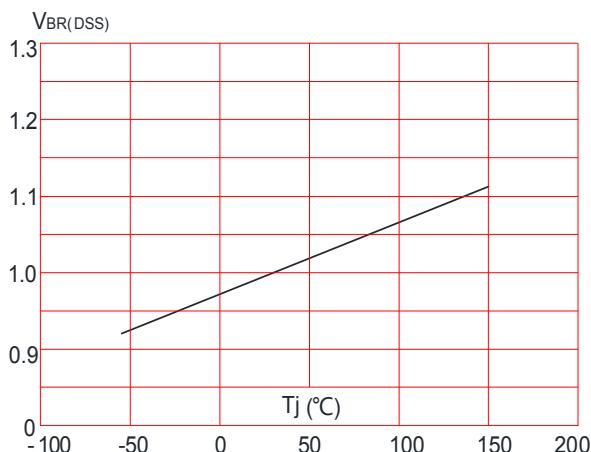


Figure 9: Maximum Safe Operating Area

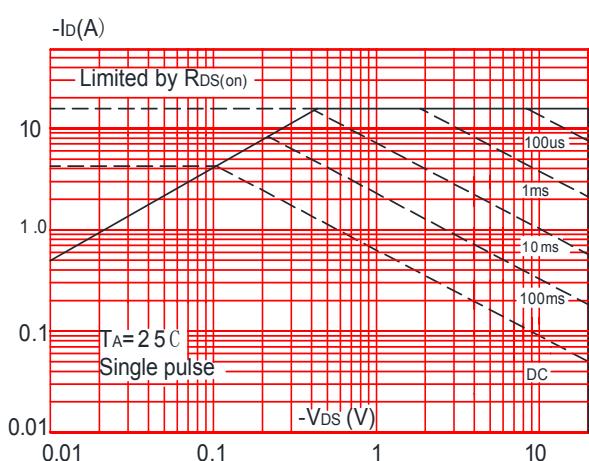


Figure. 11 : Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

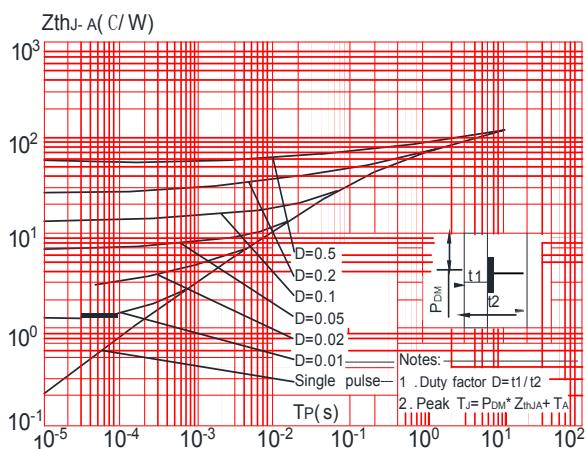


Figure 8: Normalized on Resistance vs. Junction Temperature

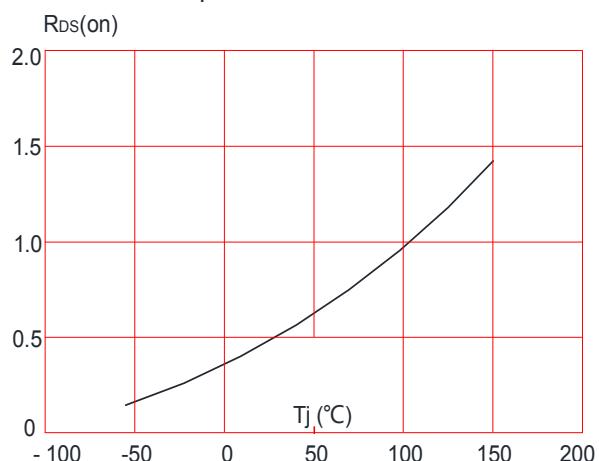
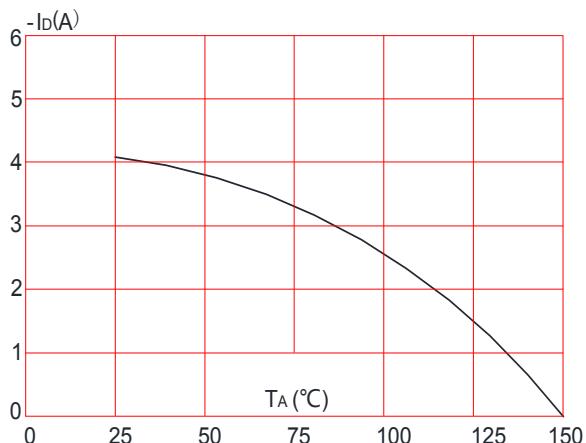
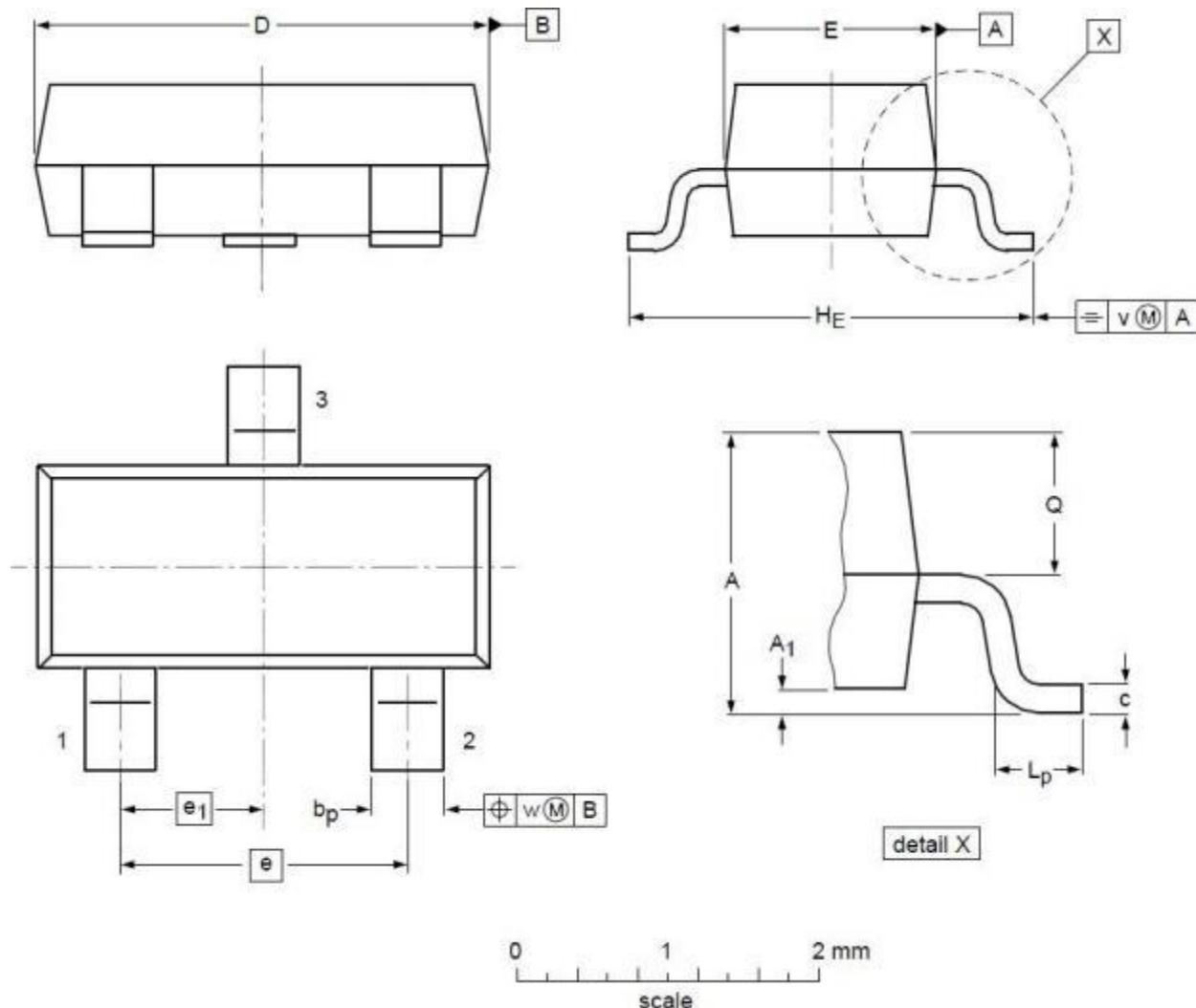


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature





Package Mechanical Data-SOT-23



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.01	1.15	A₁	0.01	0.05	0.10
b_p	0.30	0.42	0.50	c	0.08	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e₁	--	0.95	--
H_E	2.25	2.40	2.55	L_p	0.30	0.42	0.50
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				